
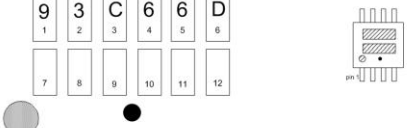




<b>Title of Change:</b>	CAT93C66VI-GT3 FAB Transfer LAPIS (formerly OKI) to Gresham.																			
<b>Proposed First Ship date:</b>	19 December 2019																			
<b>Contact Information:</b>	Contact your local ON Semiconductor Sales Office or <Ovidiu.Tol@onsemi.com>																			
<b>Samples:</b>	Contact your local ON Semiconductor Sales Office or <PCN.Samples@onsemi.com> Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.																			
<b>Type of Notification:</b>	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <PCN.Support@onsemi.com>																			
<b>Change Part Identification:</b>	Affected product will be marked with new plant code.																			
<b>Change Category:</b>	<input checked="" type="checkbox"/> Wafer Fab Change <input checked="" type="checkbox"/> Assembly Change <input checked="" type="checkbox"/> Test Change <input type="checkbox"/> Other _____																			
<b>Change Sub-Category(s):</b>	<input type="checkbox"/> Manufacturing Site Addition <input checked="" type="checkbox"/> Material Change <input checked="" type="checkbox"/> Datasheet/Product Doc change <input type="checkbox"/> Manufacturing Site Transfer <input type="checkbox"/> Product specific change <input checked="" type="checkbox"/> Shipping/Packaging/Marking <input checked="" type="checkbox"/> Manufacturing Process Change <input type="checkbox"/> Other: _____																			
<b>Sites Affected:</b>	ON Semiconductor Sites: ON S. Philippines ON S. Gresham, Oregon, US	External Foundry/Subcon Sites: Subcons Thailand External Foundry Japan																		
<b>Description and Purpose:</b>																				
Qualify new die source for CAT93C66 to support customer demand.																				
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**Datasheet change:**

The original datasheet will be left active on the www.onsemi.com customer web site for comparison purposes until the FPCN expires. The new datasheet will become visible on the web site on that FPCN expiration.

Removed all the references to extended temp range (125°C).

**Qualification Plan:**

**QV DEVICE NAME:** CAT93C66VI-GT3  
**RMS:** 60123  
**PACKAGE:** 8L SOIC

Test	Specification	Condition	Interval
EDR/HTSL	AEC Q100-005	Endurance preconditioning - 1 Mil cycles@ Room temp, High Temp Data Retention: Ta=150°C for 1008 hrs.	1008 hrs
HTOL	JA108	TA=150C, bias at 1.2X Nominal (not to exceed Max rated) (NVM endurance 1 Million cycle preconditioning must be performed prior to HTOL stress.)	504 hrs
ELFR	AECQ100-008	TA=150C, bias at 1.2X Nominal (not to exceed Max rated)	24 hrs
PC	J STD 020A, JESD22-A113	Solder reflow MSL 1 at 260C	
HAST	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 100% of rated V or 100V max	96 hrs
TC	JESD22-A104	Temp = -65°C to +150°C	500 cycles
UHAST	JESD22-A118	Temp = 130C, RH=85%, ~18.8 psig	96 hrs
SAT	12MSB17722C	Scanning Acoustical Topography ,Pre post MSL, TC500	
DPA	AEC-Q101-004 Section 4	Destructive Physical Analysis, Post TC, HAST, HTOL	
CDPA WP	12MSB17722C	Custom Destructive Physical Analysis - Wire Pull Post TC	

Estimated date for qualification completion: 7 October 2019



**List of Affected Part:**

**Note:** Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the **PCN Customized Portal**.

Part Number	Qualification Vehicle
CAT93C66VI-GT3	CAT93C66VI-GT3

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**Appendix A: Changed Products**

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Product	Customer Part Number	Qualification Vehicle
CAT93C66VI-GT3		CAT93C66VI-GT3